IPC ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES®	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			der both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.											
752-21.1					Form Type Distribute	* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					rials and Mf	ials and Mfg Information				
upplier Informa	tion															
Company name*			Company unique ID			Ţ	Unique ID Authority					Response Date*				
nsemi											2024-05-	2024-05-04				
Contact Name			Title - Contact			I	Phone - Contact*				Email - Contact*					
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Product-Env-Stewards			Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com					
Requester I	Item Number	Mfr Item Number		Mfr Item Name			Effective Date	Version Manufacturing Site		V	Veight*	UOM	Unit Type			
		SMA5101-TL-H Si MMIC		Si MMIC DOUBLE	MMIC DOUBLE BAL MIX IC		2024-05-04		(CNG		.9	mg	Each		
	roccess Informatio		amain al Daga	Aller	STD-020 MSI	Dating	Pools Puos	paga Daday	Tommountu	May Time at Book	Tomamorate	wo Nivers	ber of Reflow Cyc	das		
2			Terminal Base Alloy J-STI CU Alloy 1		STD-020 MSL	_ Kaung	Peak Process Body Temp			ature Max Time at Peak Ter 30			ber of Reflow Cyc	cies		
			U Alloy	I			200		IC	30	second	ls 3				
omments		J	J	20												
	ne at peak temperature															
for more information	regarding material cor	nposition p	olease refer t	o page 3												

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.1	mg	Supplier	Silicon (Si)	7440-21-3		0.1	mg
Lead Frame	3.17	mg	Supplier	Silver (Ag)	7440-22-4		0.0669	mg
			Supplier	Zinc (Zn)	7440-66-6		0.006	mg
			В	Nickel (Ni)	7440-02-0		0.0114	mg
			Supplier	Iron (Fe)	7439-89-6		0.0802	mg
			Supplier	Copper (Cu)	7440-50-8		3.001	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0044	mg
Mold Compound-Black	4.48	mg		Epoxy Phenol Resin	proprietary data		0.0358	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0448	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		0.2688	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		3.584	mg
			Supplier	Ortho-Cresol Novolac Resin	29690-82-2		0.5376	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		0.009	mg
Plating	0.1	mg	В	Bismuth (Bi)	7440-69-9		0.0006	mg
			Supplier	Tin (Sn)	7440-31-5		0.0994	mg
Wire Bond - Au	0.05	mg	Supplier	Gold (Au)	7440-57-5		0.05	mg